

ABSTRACT

**SEMICONDUCTOR MULTI-PACKAGE MODULE INCLUDING STACKED-DIE PACKAGE
AND HAVING WIRE BOND INTERCONNECT BETWEEN STACKED PACKAGES**

A semiconductor multi-package module having stacked first and second packages, each package including a die attached to a substrate, in which the first and second substrates are interconnected by wire bonding, and wherein at least one said package comprises a stacked die package. Also, a method for making a semiconductor multi-package module, by providing a stacked die molded first package including a first package substrate, affixing a second molded package including a second substrate onto an upper surface of the first package, and forming z-interconnects between the first and second substrates.